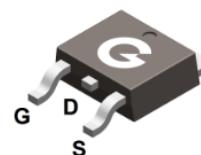
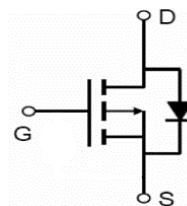


Features

- Super low gate charge
- 100% E_{AS} guaranteed
- Excellent C_{dv/dt} effect decline
- Advanced high cell density Trench technology
- Halogen free
- Qualified to AEC-Q101 standards for high reliability

HF

TO-252

Mechanical Data

- Case: TO-252
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
TBL950P10D	TO-252	80 pcs / Tube or 2500 pcs / Tape & Reel	950P10D

Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V _{DSS}	-100	V
Gate-to-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current (T _c = 25°C) ^{*1}	I _D	-30	A
Continuous Drain Current (T _c = 100°C) ^{*1}		-21	A
Pulsed Drain Current ^{*2}	I _{DM}	-52	A
Single Pulse Avalanche Energy ^{*3}	E _{AS}	110	mJ

Thermal Characteristics

Parameter	Symbol	Value	Unit
Power Dissipation (T _c = 25°C)	P _D	69.3	W
Thermal Resistance Junction-to-Case	R _{θJC}	1.8	°C/W
Operating Junction Temperature Range	T _J	-55 ~ +150	°C
Storage Temperature Range	T _{STG}	-55 ~ +150	°C

Electrical Characteristics (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = -250\mu\text{A}$	-100	-	-	V
$I_{DS(0)}$	Zero Gate Voltage Drain Current	$V_{DS} = -100V, V_{GS} = 0V, T_C = 25^\circ\text{C}$	-	-	-50	μA
		$V_{DS} = -100V, V_{GS} = 0V, T_C = 55^\circ\text{C}$	-	-	-60	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	± 100	nA
On Characteristics						
$R_{DS(ON)}$	Static Drain-Source On-resistance ^{*2}	$V_{GS} = -10V, I_D = -12\text{A}$	-	-	95	$\text{m}\Omega$
		$V_{GS} = -4.5V, I_D = -9\text{A}$	-	-	115	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1	-	-2.5	V
Dynamic Characteristics						
C_{ISS}	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = -20V$ $f = 1.0\text{MHz}$	-	3029	-	pF
C_{OSS}	Output Capacitance		-	129	-	
C_{RSS}	Reverse Transfer Capacitance		-	76	-	
Switching Characteristics						
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD} = -50V$ $I_D = -10\text{A}$ $V_{GS} = -10V$ $R_G = 3.3\Omega$	-	12	-	ns
t_r	Turn-on Rise Time		-	27.4	-	
$t_{d(OFF)}$	Turn-Off Delay Time		-	79	-	
t_f	Turn-Off Fall Time		-	53.6	-	
Q_G	Total Gate-Charge	$V_{DS} = -50V$ $I_D = -20\text{A}$ $V_{GS} = -10V$	-	44.5	-	nC
Q_{GS}	Gate to Source Charge		-	9.13	-	
Q_{GD}	Gate to Drain (Miller) Charge		-	5.93	-	
Source-Drain Diode Characteristics						
V_{SD}	Diode Forward Voltage	$I_{SD} = -1A, V_{GS} = 0V$	-	-	-1.2	V
I_S	Source-Drain Current(Body Diode) ^{*1,4}		-	-	-30	A
I_{SM}	Pulsed Source-Drain Current(Body Diode) ^{*2, 4}		-	-	-52	A
t_{rr}	Reverse Recovery Time	$T_J = 25^\circ\text{C}, I_F = -14\text{A}$ $di/dt = -100\text{A}/\mu\text{s}$	-	38.7	-	nS
Q_{rr}	Reverse Recovery Charge		-	22.4	-	nC

Notes:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
3. The E_{AS} data shows Max. rating. The test condition is $V_{DD} = -25V, V_{GS} = -10V, L = 0.85\text{mH}$
4. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

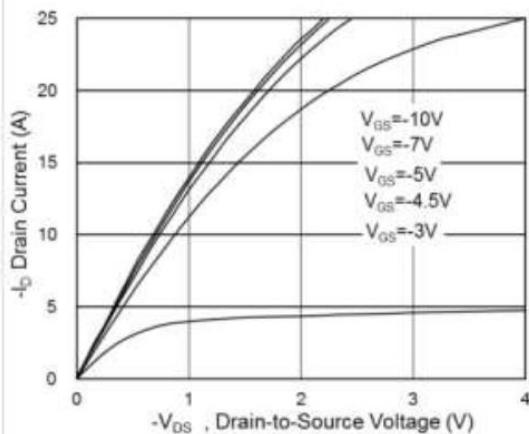


Fig.1 Typical Output Characteristics

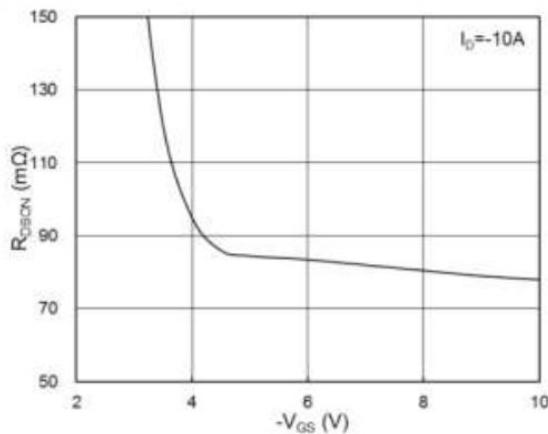


Fig.2 On-Resistance vs. G-S Voltage

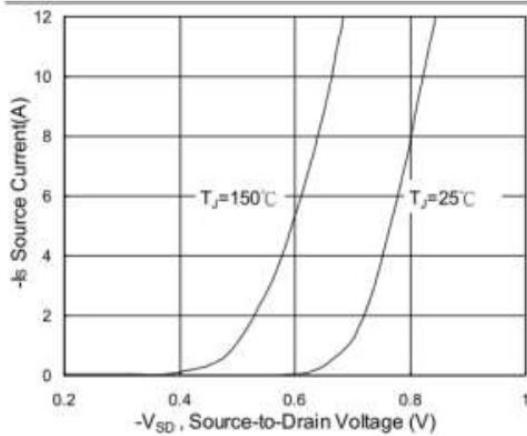


Fig.3 Forward Characteristics Of Reverse

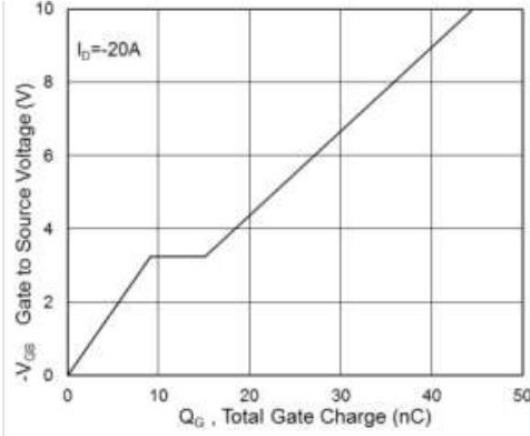


Fig.4 Gate-Charge Characteristics

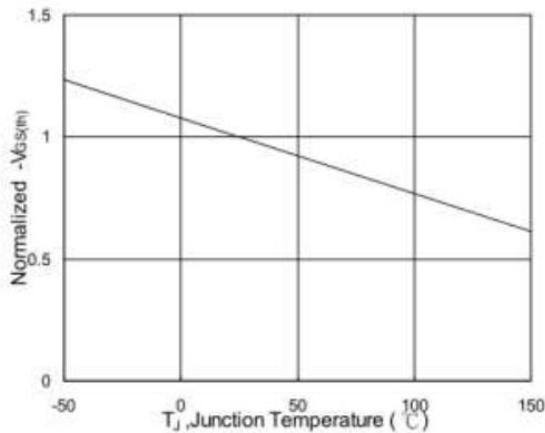


Fig.5 Normalized $V_{GS(\text{th})}$ vs. T_J

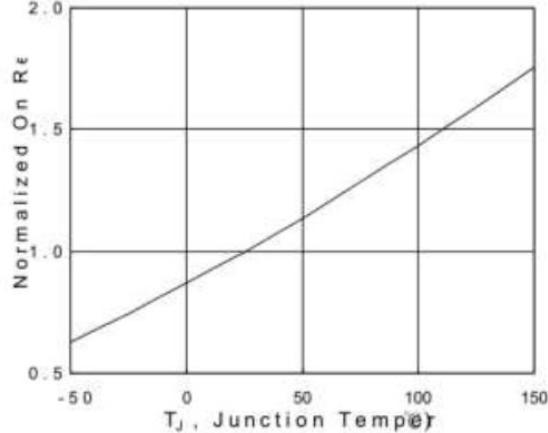


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

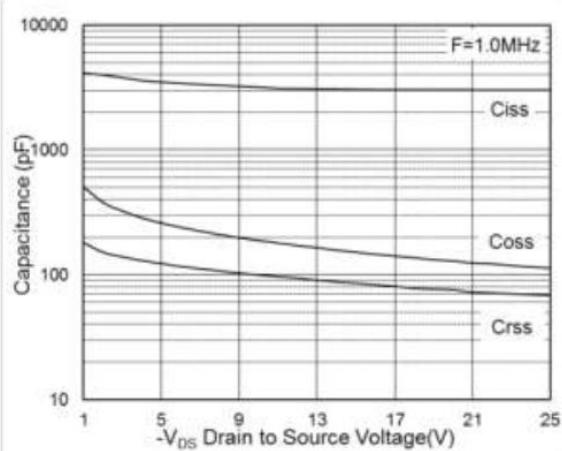


Fig.7 Capacitance

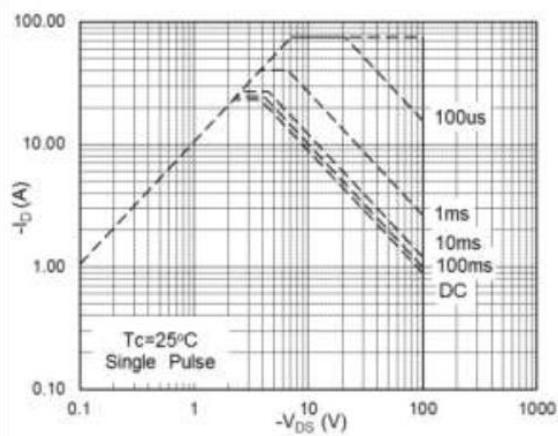
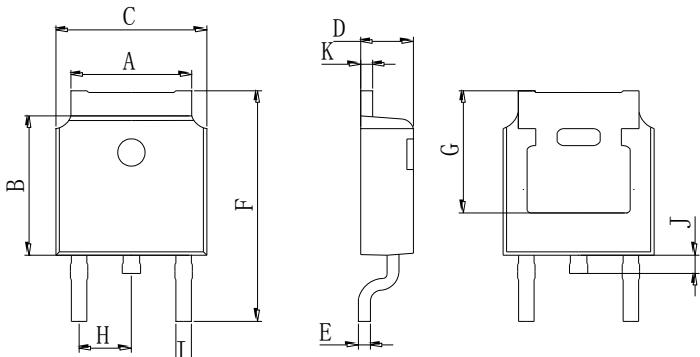


Fig.8 Safe Operating Area

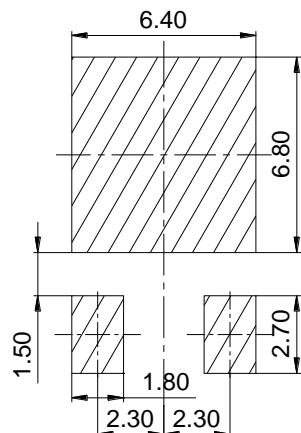
Package Outline Dimensions (Unit: mm)



TO-252		
Dimension	Min.	Max.
A	5.05	5.65
B	5.80	6.40
C	6.25	6.85
D	2.20	2.40
E	0.40	0.60
F	9.71	10.31
G	5.05	5.65
H	2.10	2.50
I	0.70	0.90
J	0.50	0.70
K	0.40	0.60

Mounting Pad Layout (Unit: mm)

TO-252



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